MA3X727 (MA727)

Silicon epitaxial planar type

For super high speed switching For small current rectification

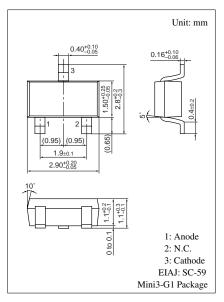
■ Features

- $V_R = 50 \text{ V}$ is guaranteed
- $I_{F(AV)} = 200$ mA rectification is possible
- Mini type 3-pin package

■ Absolute Maximum Ratings $T_a = 25$ °C

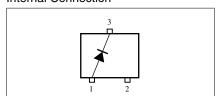
| Parameter | Symbol | Rating | Unit |
|---|--------------------|-------------|------|
| Reverse voltage (DC) | V_R | 50 | V |
| Repetitive peak reverse-voltage | V_{RRM} | 50 | V |
| Peak forward current | I_{FM} | 300 | mA |
| Average forward current | I _{F(AV)} | 200 | mA |
| Non-repetitive peak forward- surge-current * | I_{FSM} | 1 | A |
| Junction temperature | T _j | 150 | °C |
| Storage temperature | T_{stg} | -55 to +150 | °C |

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



Marking Symbol: M1Z

Internal Connection



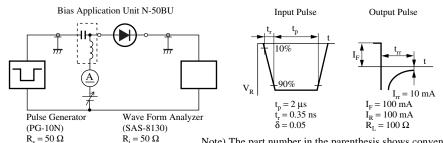
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■ Electrical Characteristics $T_a = 25$ °C

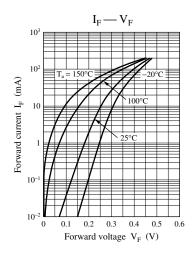
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|-------------------------|-----------------|--|-----|-----|------|------|
| Reverse current (DC) | I_R | $V_R = 50 \text{ V}$ | | | 200 | μΑ |
| Forward voltage (DC) | V _{F1} | $I_F = 30 \text{ mA}$ | | | 0.36 | V |
| | V_{F2} | $I_F = 200 \text{ mA}$ | | | 0.55 | V |
| Terminal capacitance | C _t | $V_R = 0 V, f = 1 MHz$ | | 30 | | pF |
| Reverse recovery time * | t _{rr} | $I_F = I_R = 100 \text{ mA}$ | | 3.0 | | ns |
| | | $I_{rr} = 10 \text{ mA}, R_{L} = 100 \Omega$ | | | | |

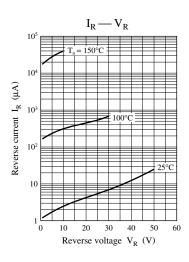
Note) 1. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

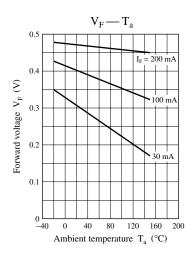
- 2. Rated input/output frequency: 1 GHz
- 3. *: t_{rr} measuring instrument

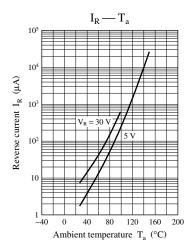


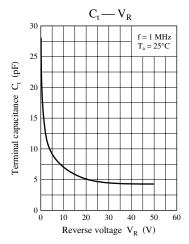
 $R_i = 50 \Omega$ Note) The part number in the parenthesis shows conventional part number.











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